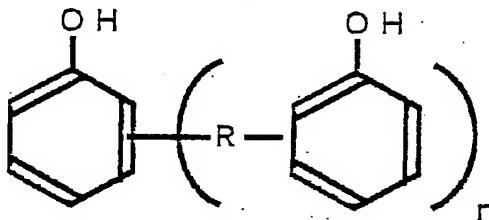


## ABSTRACT

The present invention provides a resin-coated copper foil, which does not form a crack in the filled resin layer due to thermal shock in a soldering step or the like, when the resin of the resin-coated copper foil has filled via holes. The present invention provides a resin-coated copper foil having the resin layer on one side of the copper foil, wherein the resin composition of the resin layer comprises (1) 20 to 70 parts by weight of an epoxy resin, (2) 5 to 30 parts by weight of a high polymer having a crosslinkable functional group in the molecule and a crosslinking agent therefor in combination, and (3) 10 to 10 60 parts by weight of a compound having a structure shown in Formula 1.

### Formula 1

15



, wherein n is an integer of one or more.